



Material Content Data Sheet



Sales Product Name	TLD1211SJ			Issued	3. July 2019			
MA#	MA005348230							
Package	PG-DSO-8-16			Weight*	82.97 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.290	1.55	1.55	15544	15544
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		108	
	non noble metal	zinc	7440-66-6	0.036	0.04		432	
	non noble metal	iron	7439-89-6	0.717	0.86		8644	
wire	non noble metal	copper	7440-50-8	29.121	35.10	36.01	350974	360158
	noble metal	gold	7440-57-5	0.085	0.10	0.10	1021	1021
	encapsulation	organic material	carbon black	1333-86-4	0.099	0.12		1188
encapsulation	plastics	epoxy resin	-	4.534	5.46		54649	
	inorganic material	silicondioxide	60676-86-0	44.653	53.83	59.41	538172	594009
leadfinish	non noble metal	tin	7440-31-5	0.814	0.98	0.98	9809	9809
plating	noble metal	silver	7440-22-4	0.650	0.78	0.78	7837	7837
glue	plastics	acrylic resin	-	0.212	0.26		2557	
	noble metal	silver	7440-22-4	0.752	0.91	1.17	9065	11622
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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